

Conference programme

SUNDAY, 23 SEPTEMBER 2018

Since 16.00	Registration
19.00 - 21.00	Dinner (Restauracja)

MONDAY, 24 SEPTEMBER 2018

07.30-09.00	Breakfast (Restauracja)
09.15 - 9.30	Conference opening (Sala Górna)
09.30 – 11.00	Plenary Session 1 (Sala Górna) Chairman: Małgorzata Jakubowska (Warsaw University of Technology, Poland)
09.30 - 10.00	"Institute of Electronics at the Silesian University of Technology – yesterday and today" - Zdzisław Filus (Silesian University of Technology, Institute of Electronics, Gliwice, Poland)
10.00 - 10.30	"Modelling thermal properties of large LED modules" - Przemysław Ptak Górecki Krzysztof, Dziurdzia Barbara
10.30 - 11.00	"The vapour phase soldering (VPS) technology: a review" - Illes Balazs , Géczy Attila, Harsányi Gábor
11.00 – 11.30	Coffee break (Sala Górna, Sala Kolumnowa)
11.30 – 13.00	Poster session 1 (Sala Kolumnowa)
Abstract 101	Filipowski Wojciech - Model of phosphorus diffusion in silicon for highly doped solar cell emitter layer
Abstract 102	Filipowski Wojciech, Pruszowski Zbigniew, Niemiec Natalia, Kowalik Piotr, Waczyński Krzysztof - The influence of structure and morphology of resistive layer on electrical parameters of resistors based on amorphous Ni-Cu-P alloy obtained by electroless metallization
Abstract 103	Drzozga Kamila Anna, Bałuta Sylwia, Nawrot Witold, Cabaj Joanna, Malecha Karol - Novel fluoresceine-based biosensor for sensitive optical detection of β 17-estradiol
Abstract 104	Witek Krzysztof, Skwarek Agata, Guzdek Piotr, Rzepka Marek - Polymer-Silver Heaters as Infrared Radiation Sources Used in Birds Breeding
Abstract 105	Dąbrowski Arkadiusz, Dzięgielewski Maciej - <i>Impact of firing temperature on insulating properties of Low</i>

	<i>Temperature Cofired Ceramics</i>
Abstract 106	Krammer Oliver, Martinek Péter, Illés Balázs, Jakab László - <i>Machine learning based prediction of component self-alignment in vapour phase and infrared soldering</i>
Abstract 107	Pietrikova Alena, Girasek Tomas, Durisin Juraj, Livovsky Lubomir, Saksl Karel - <i>Joints realised by sintering of pressureless Ag paste</i>
Abstract 108	Livovsky Lubomir, Pietrikova Alena - <i>Measurement and regulation of saturated vapour height level in VPS chamber</i>
Abstract 109	Turkiewicz Marta, Nowak Damian, Stafiniak Andrzej - <i>Thermoelectric properties of germanium thin films doped with antimony</i>
Abstract 110	Zuk Samuel, Pietrikova Alena, Vehec Igor - <i>Analysis of polymer paste 's behaviour in specific sensor applications</i>
Abstract 117	Nawrot Witold, Malecha Karol - <i>Preliminary Studies for Hybrid LTCC-PDMS Fluorescence Sensor</i>
Abstract 118	Sitek Janusz, Kościelski Marek, Stęplewski Wojciech, Karolewski Sebastian, Rafalik Ireneusz, Lipiec Krzysztof, Serzysko Tomasz - <i>The influence of materials and technological parameters on IMC growth speed and thickness at solder joints in SMT for special applications</i>
Abstract 119	Jasinska Laura, Macioszczyk Jan, Malecha Karol - <i>Influence of the screen printing parameters geometry of the conductive paths deposited on the LTCC substrate</i>
Abstract 120	Géczy Attila, Sipos András, Kiss András, Gyarmati Dániel, Straubinger Dániel, Rigler Dániel, Krammer Oliver - <i>Advances on high current load effects on SMD resistor and BGA lead-free solder joints</i>
Abstract 121	Dybowska-Sarapuk Lucja, Janczak Daniel, Słoma Marcin, Jakubowska Małgorzata - <i>Electrical and rheological percolation threshold of the graphene screen printing pastes</i>
Abstract 122	Potencki Jerzy, Tomaszewski Grzegorz, Bład Grzegorz, Gajór Grzegorz, Pietrikova Alena, Lukacs Peter - <i>Investigation of Inkjet Printed Path Resistance in the Context of Manufacture and Flexible Application</i>
Abstract 123	Jasiński Michał, Rezmer Jacek, Sikorski Tomasz, Szymańda Jarosław - <i>Monitoring of photovoltaic systems in point of integration with electricity network</i>
Abstract 125	Al-Ma'aiteh Tareq Ibrahim, Krammer Oliver - <i>Non-Newtonian Numerical Modelling of Solder Paste Viscosity</i>

	<i>Measurement</i>
Abstract 126	Alaya Mohamed Amine, Geczy Attila, Illes Balazs, Harsanyi Gabor - <i>Workspace identification of Vapour Phase Soldering with Sensor Fusion Method</i>
Abstract 127	Hirman Martin, Navratil Jiri, Steiner Frantisek, Dzugan Tomas, Hamacek Ales - <i>Connection of SMD Chip Resistors on a Flexible Substrate by Non-Conductive Adhesive</i>
13:00 – 14:30	Lunch (Sala Bankietowa)
14:30 – 16:00	Plenary Session 2 (Sala Górna) Chairman: Agata Skwarek (Institute of Electron Technology, Poland)
14:30 – 15:00	"Corelation between microstructure and gas sensitive properties of zinc oxide" - Marta Fiedot-Toboła, Kamila Startek, Patrycja Suchorska-Woźniak, Olga Rac-Rumijowska, Helena Teterycz
15:00 – 15:30	"Development and application of a mixed thick- / thin film thermopiles based on constantan/silver" - Mirośław Gierczak , Dzedzic Andrzej
15:30 – 16:00	"Carbon nanotube based electrical conductors" - Agnieszka Łękawa-Raus
16:00 – 16:15	Coffee break (Sala Górna, Sala Kolumnowa)
16:15 – 17:45	Poster session 2 (Sala Kolumnowa)
Abstract 129	Górecki Paweł, Górecki, Krzysztof, Myśliwiec Marcin, Kisiel Ryszard - <i>Thermal parameters of monocrystalline GaN Schottky diodes</i>
Abstract 130	Sobik Piotr, Pawłowski Radosław, Pluta Anna, Jeremiasz Olgierd, Kulesza-Matlak Grażyna, Drabczyk Kazimierz, Zięba Paweł - <i>The impact of ribbon treatment on the interconnections of solar cells within a glass free PV module</i>
Abstract 131	Filipowski Wojciech, Pruszowski Zbigniew, Niemiec Natalia, Kowalik Piotr, Waczyński Krzysztof - <i>Influence of sodium cytrin concentration in metallization baths on Ni-Cu-P resistive layer properties</i>
Abstract 134	Hlina Jiří, Reboun Jan, Hermansky Vojtech, Simonovsky Marek, Johan Jan, Hamáček Aleš - <i>Co-fired multilayer thick printed copper structures</i>
Abstract 135	Navratil Jiří, Hirman Martin, Dzugan Tomas, Steiner František, Hamáček Aleš - <i>Non-Conductive Adhesive</i>

	<i>Connected QFN Chips on Screen Printed Pattern and Interconnection Reliability Testing</i>
Abstract 138	Benešová Andrea, Hirman Martin, Šíma Karel, Hamáček Aleš, Tupa Jiří, Steiner František - <i>IoT unit for reliability improvement during of the product life cycle</i>
Abstract 139	Podsiadły Bartłomiej Jakub, Skalski Andrzej, Słoma Marcin - <i>Electrically conductive copper-based composite filaments for Fused Deposition Modeling</i>
Abstract 140	Walter Piotr Aureliusz, Peplowski Andrzej, Górski Łukasz, Janczak Daniel, Jakubowska Małgorzata - <i>Disposable, screen-printed acetylcholinesterase electrodes for the determination of organophosphorus pesticides</i>
Abstract 140	Wałpuski Bartłomiej, Szałapak Jerzy, Słoma Marcin - <i>Conductive paths and connections on polymer substrates for structural electronics</i>
Abstract 143	Krzemiński Jakub, Wroblewski Grzegorz, Skalski Andrzej, Słoma Marcin, Jakubowska Małgorzata - <i>Photonic curing of aerosol printed lines on the ABS substrate</i>
Abstract 144	Drabczyk Kazimierz, Starowicz Zbigniew, Gawlińska Katarzyna, Sobik Piotr - <i>Study of lamination quality of solar modules with PMMA front layer</i>
Abstract 146	Sabat Wiesław, Klepacki Dariusz, Kamuda Kazimierz, Kuryło Kazimierz - <i>Signal integrity in microelectronic hybrid systems made on metal substrates</i>
Abstract 201	Sobolewski Maciej, Dziurdzia Barbara - <i>New experimental approach to void phenomena in SMT joints</i>
Abstract 202	Kuryło Kazimierz, Sabat Wiesław, Klepacki Dariusz, Kamuda Kazimierz - <i>Comparison of emission measurement methods for electromagnetic disturbances in the frequency range from 30 to 300 MHz for LED lamps according to PN-EN 55015 standard</i>
Abstract 202	Hubacz Marcin, Kuryło Kazimierz, Pawłowicz Bartosz, Sabat Wiesław, Trybus Bartosz, Klepacki Dariusz - <i>Analysis of Electromagnetic Disturbances Generated by an Autonomous RFID-Based Navigation Robot</i>
Abstract 204	Dziurdzia Barbara, Sobolewski Maciej, Mikołajek Janusz - <i>Novel solder pastes in respect to void formation on the example of LED assembly</i>
Abstract 205	Swatowska Barbara, Panek Piotr, Drygała Aleksandra, Światłowska Julita - <i>The properties of mono- and</i>

	<i>multicrystalline silicon solar cells with emitter of different resistance</i>
Abstract 206	Markowski Piotr - <i>Modelling of the temperature distribution in processor heat sinks</i>
Abstract 207	Matkowski Przemysław, Felba Jan - <i>Influence of pad coating on reliability of lead-free solder joints</i>
Abstract 301	Paweł Kalinowski, Łukasz Woźniak, Grzegorz Jasinski, Piotr Jasinski - <i>Drift correction of semiconductor sensors responses in electronic nose for air pollutants monitoring</i>
Abstract 302	Łukasz Woźniak, Paweł Kalinowski, Grzegorz Jasinski, Piotr Jasinski - <i>Influence of the working temperature on semiconductor gas sensor response</i>
Abstract 303	Grzegorz Jasiński, Marta Dmitrzak, Piotr Kościński, Piotr Jasiński - <i>Measurement stand for amperometric gas sensor operation temperature stabilization</i>
17:45 – 19:15	IMAPS Poland Meeting (Sala Górna)
Since 20:00	Grill Party (Altana Grillowa)
TUESDAY, 25 SEPTEMBER 2018	
7.30 - 9.00	Breakfast (Restauracja)
9.15 - 10.45	Plenary Session 3 (Sala Górna) Chairman: Andrzej Dziędzic (Wrocław University of Science and Technology, Poland)
9.15 - 9.45	"Optimization of method of synthesis of nickel-silver core-shell nanoparticles as component of conductive materials" – Anna Pajor-Świerzy, Robert Socha, Krzysztof Szczepanowicz, Radosław Pawłowski, Piotr Warszyński
9:45 – 10:15	"Laser sintering of high conductive nanosilver structures" - Hanna Wita , Bartłomiej Pawłowski, Radosław Pawłowski, Piotr Sobik, Anna Pajor-Świerzy, Małgorzata Jakubowska
10:15 – 10:45	"Influence of AlN etching process on MISFET structures" - Piotr Firek , Bartłomiej Stonio
10:45 – 11:15	Coffee break (Sala Górna)
11:15 – 12:45	Plenary Session 4 (Sala Górna) Chairman: Piotr Jasiński (Gdańsk University of Technology, Poland)
11:15 – 11:45	"Piezoresistive effect in embedded thick-film resistors" - Janusz Borecki , Jerzy Kalenik, Wojciech Stęplewski, Aneta Araźna, Kamil Janeczek

11:45 – 12:15	"Applications of the LTCC ceramics in microplasma systems" - Jan Macioszczyk , Leszek Golonka
12:15 – 12:45	"Ceramic and metal packages for SiC power devices assembly" - Ryszard Kisiel , Marcin Myśliwiec, Mariusz Sochacki
12:45 – 14:00	Lunch (<i>Sala Bankietowa</i>)
14:30 – 19:00	Sightseeing
Since 20:00	Gala Dinner (<i>Sala Kolumnowa</i>)
WEDNESDAY, 26 SEPTEMBER 2018	
8.00 - 9.30	Breakfast (<i>Restauracja</i>)
9.30 - 11.00	Plenary Session 5 (<i>Sala Górna</i>) Chairman: Karol Malecha (Wrocław University of Science and Technology, Poland)
9:30 – 10:00	"Multifunctional textile fibers for application in wearable electronics" – Olga Rac - Rumijowska
10:00 – 10:30	"The new Cu-based component of pastes for front side metallization manufacture of photovoltaic solar cells" - Małgorzata Musztyfaga-Staszuk
10:30 – 11:00	"3D printed electronic circuits from fusible alloys" - Marcin Słoma , Liubomir Bezgan
11:00 – 11:15	Coffee break (<i>Sala Górna</i>)
11:15 – 11:30	Closing session (<i>Sala Górna</i>)
12:00 – 13:00	Lunch (<i>Sala Bankietowa</i>)